ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan	PC. Bannockl	ourn, Illinois, A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declarati the declaration e	on of the su	ibstances v s all lower	within the manufactu level materials for v	urer listed which the	item. Note: manufacture	if the item is an as er has engineering	sembly with low responsibility.	
	21.1 IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mi					4fg Informa	tion		
Supplier Information														
Company name* Com			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2023-0	2023-06-08			
tact Name Title - Contact				Phone - Contact*			Email - Contact*							
Product-Env-Stewards Product Enviro			iro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repres			resentative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Product En			uct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	ersion Manufacturing Site			Weight*	UOM	Unit Type	
	NCP111	NCP1117ST18T3G ANA SO		NA SOT223 800MA LDO		2023-06-08		M	MY1		108.86	mg	Each	
Ianufacturing Proccess Informat	tion		•											
Terminal Plating / Grid Array Ma	terial 7	erminal Base A	Alloy J-STD-020 MSL Rat		L Rating	Peak Proce	Peak Process Body Temperate		ure Max Time at Peak Tempe		ture Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260 C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temperatu	re during so	dering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl halate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.1	mg	Supplier	Silicon (Si)	7440-21-3		1.1	mg
Die Attach	0.74	mg		Epoxy resin	proprietary data		0.0185	mg
			Supplier	Silver (Ag)	7440-22-4		0.6253	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0185	mg
			Supplier	Inorganic filler	Proprietary Data		0.0185	mg
			Supplier	Dicyandiamine	461-58-5		0.0037	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0555	mg
Lead Frame	37.17	mg	Supplier	Silver (Ag)	7440-22-4		0.4832	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0372	mg
			Supplier	Iron (Fe)	7439-89-6		0.8921	mg
			Supplier	Copper (Cu)	7440-50-8		35.7575	mg
Mold Compound-Black	62.4	mg		Epoxy resin	proprietary data		3.12	mg
			Supplier	Phenolic Resin	Proprietary Data		3.12	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.248	mg
			Supplier	Carbon Black (C)	1333-86-4		0.312	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		54.6	mg
Plating	7.44	mg	Supplier	Tin (Sn)	7440-31-5		7.44	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg